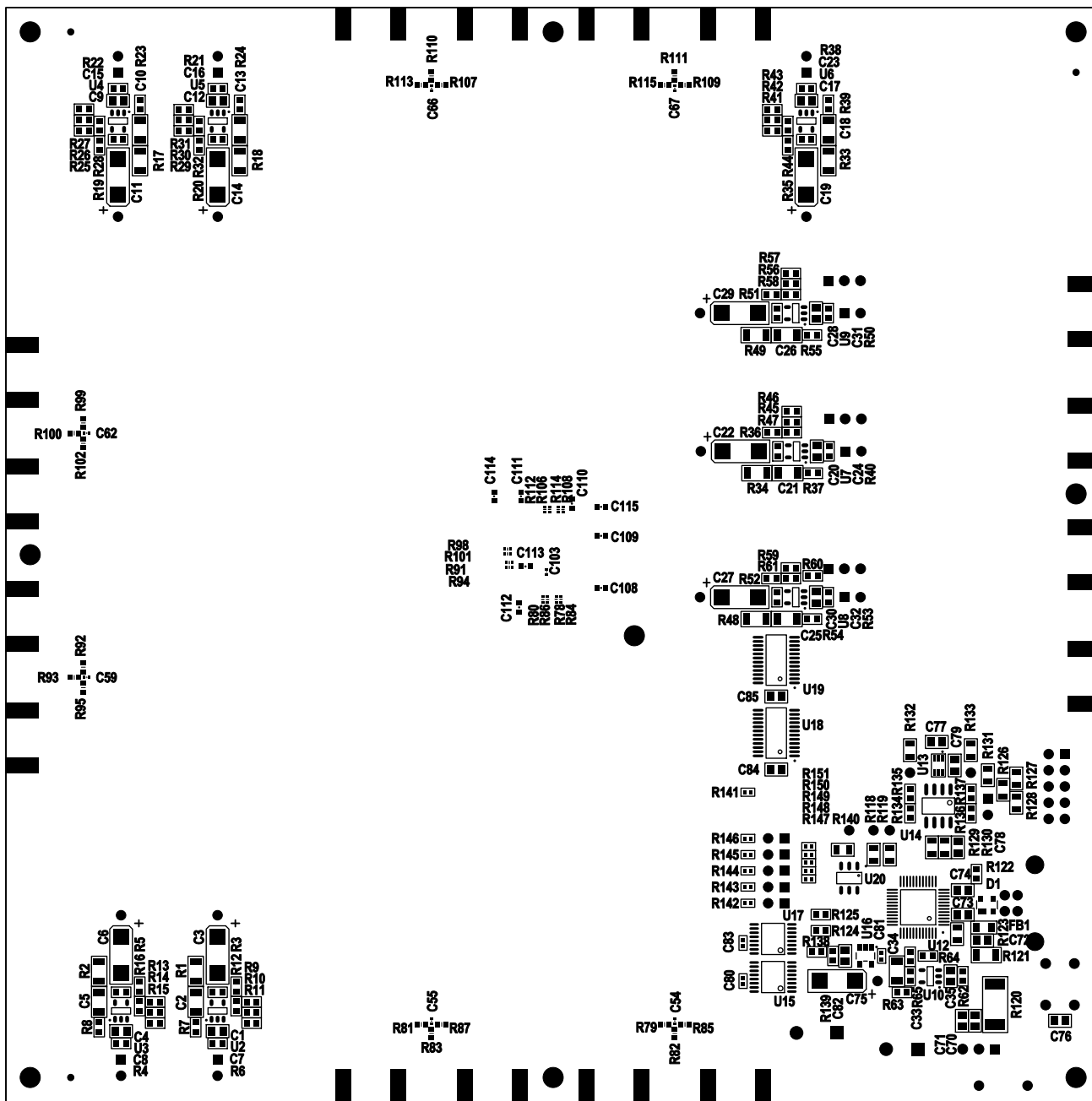
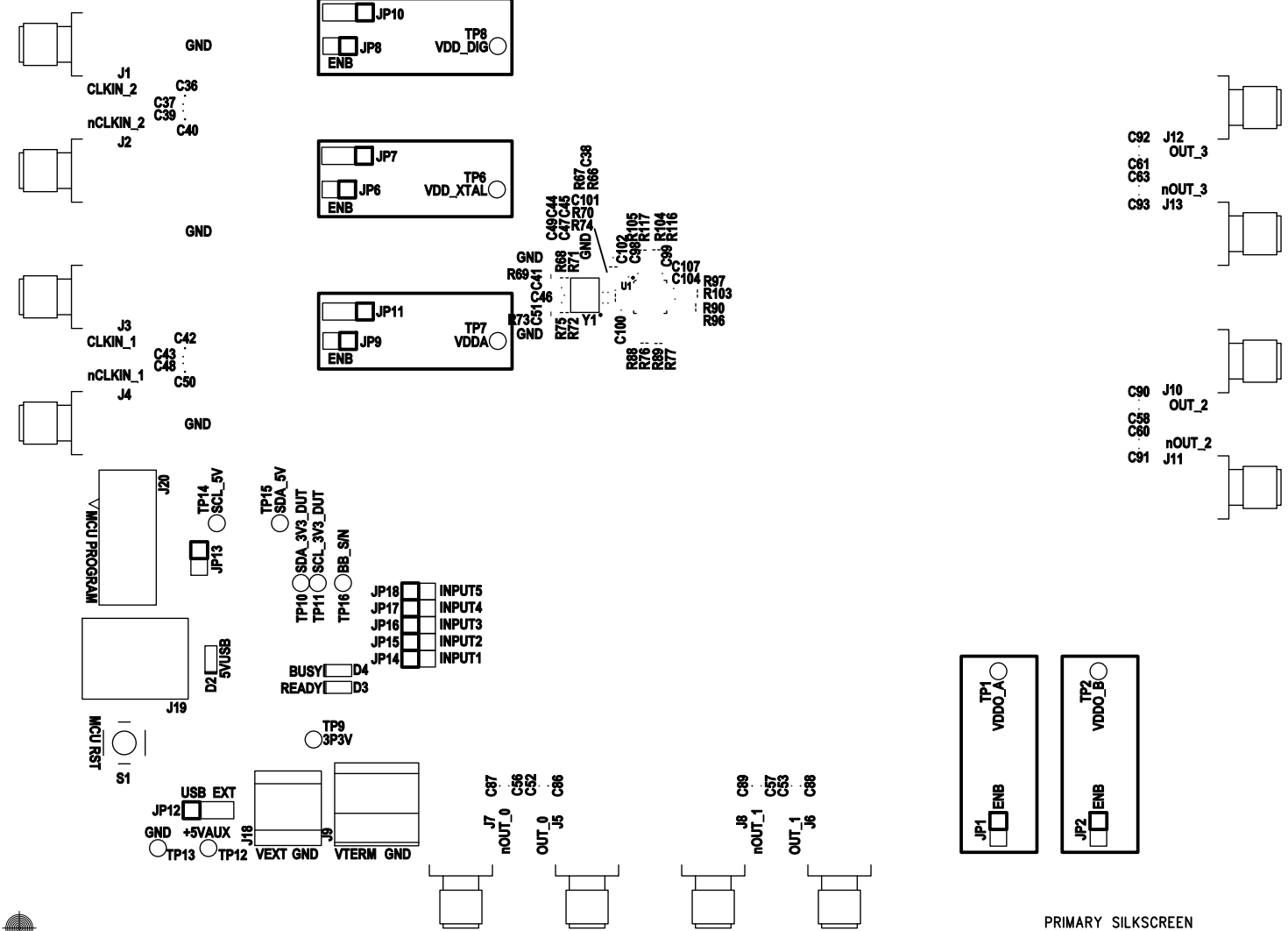


PRIMARY ASSEMBLY  
PRIMARY SILKSCREEN

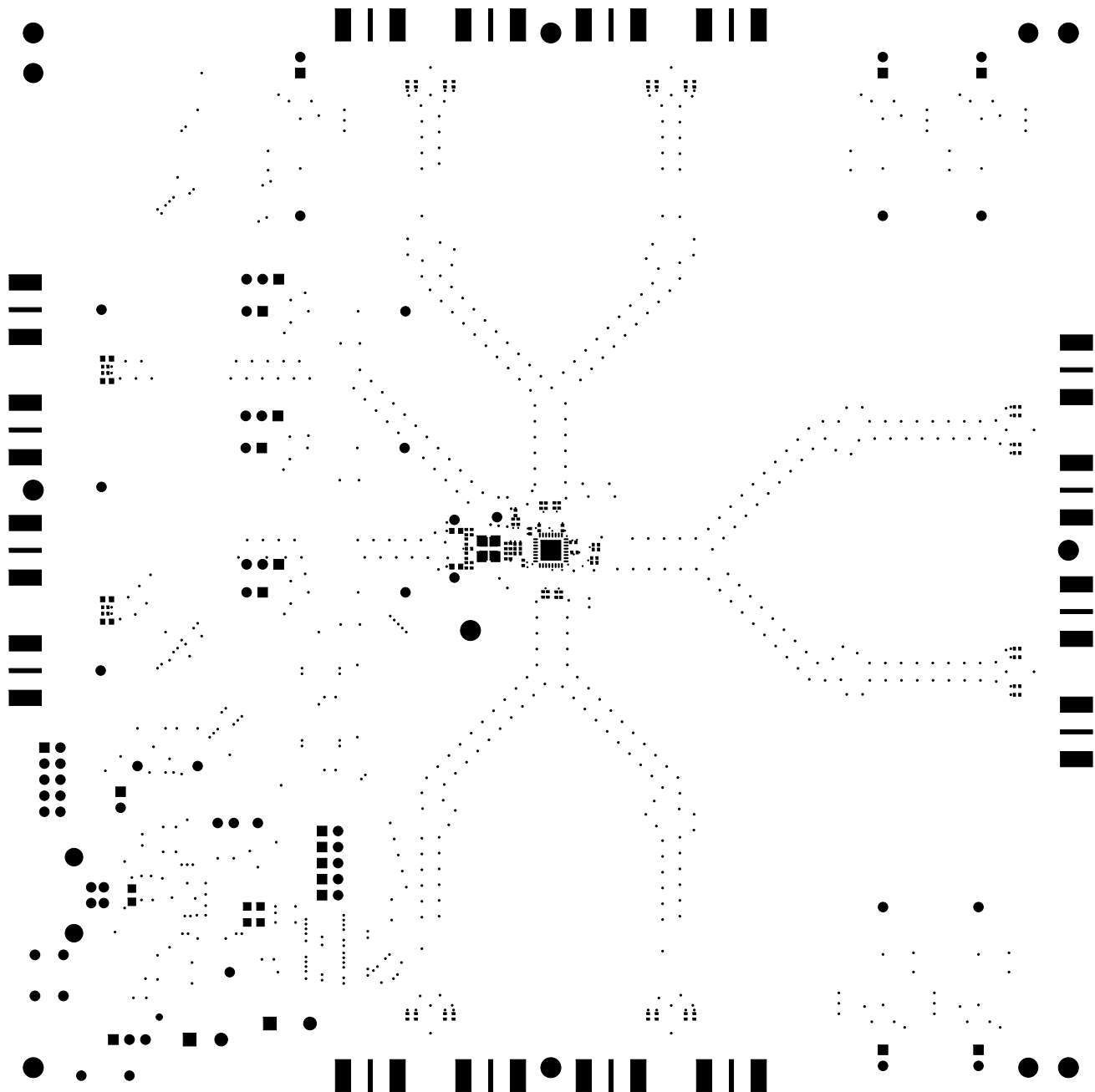


SECONDARY SILKSCREEN  
SECONDARY ASSEMBLY

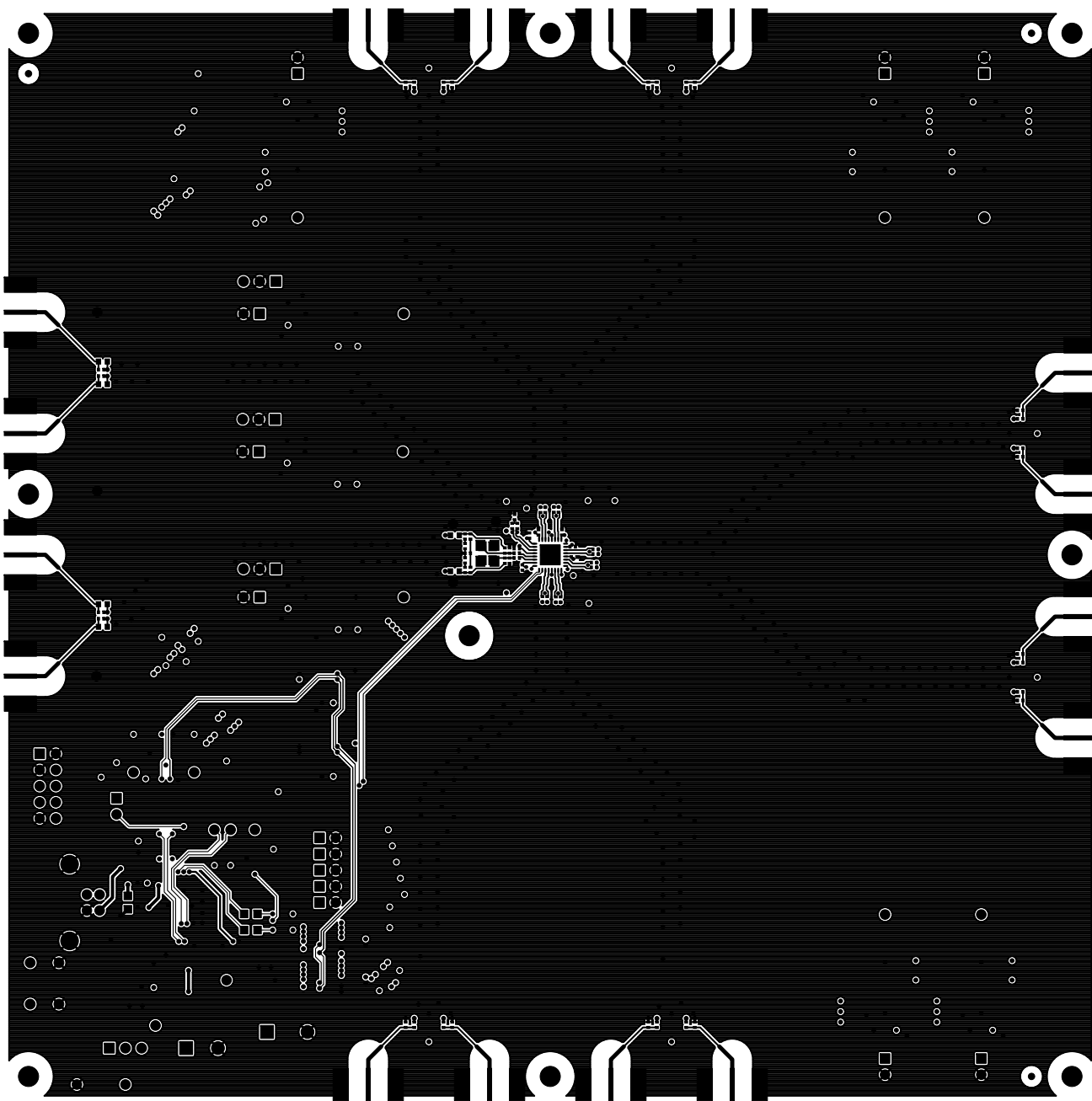


  
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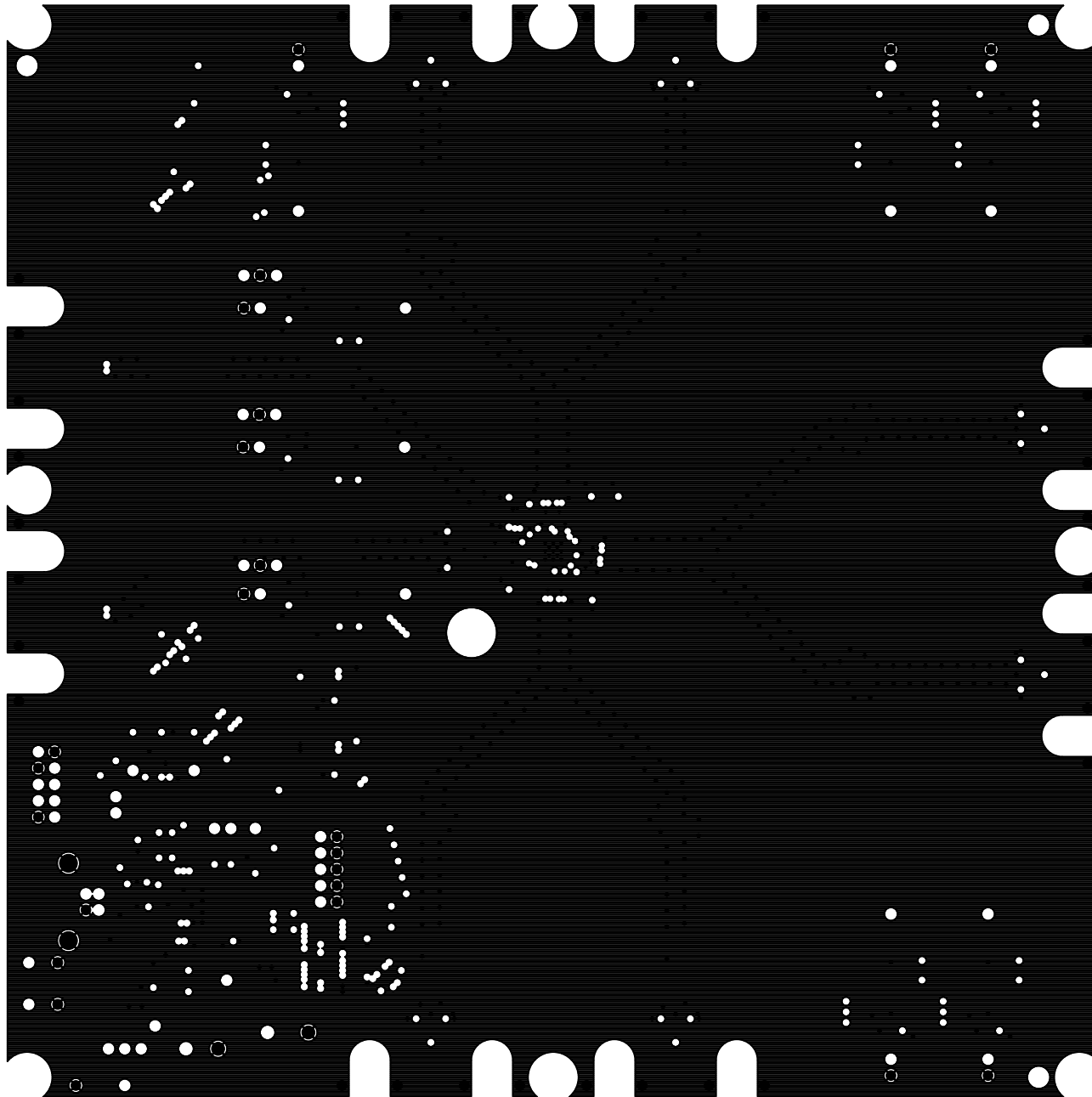
PRIMARY SILKSCREEN



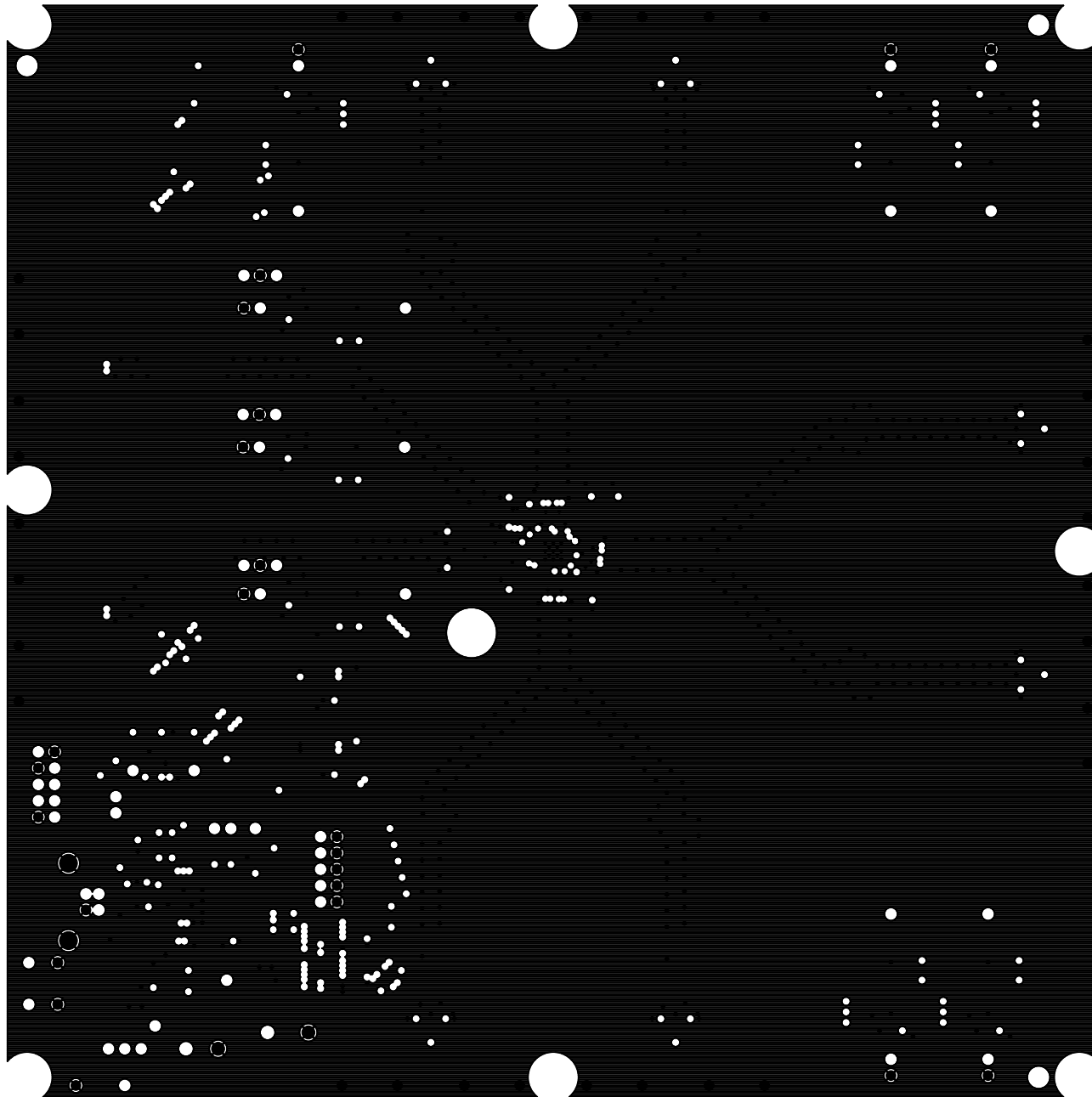
PRIMARY SOLDER MASK



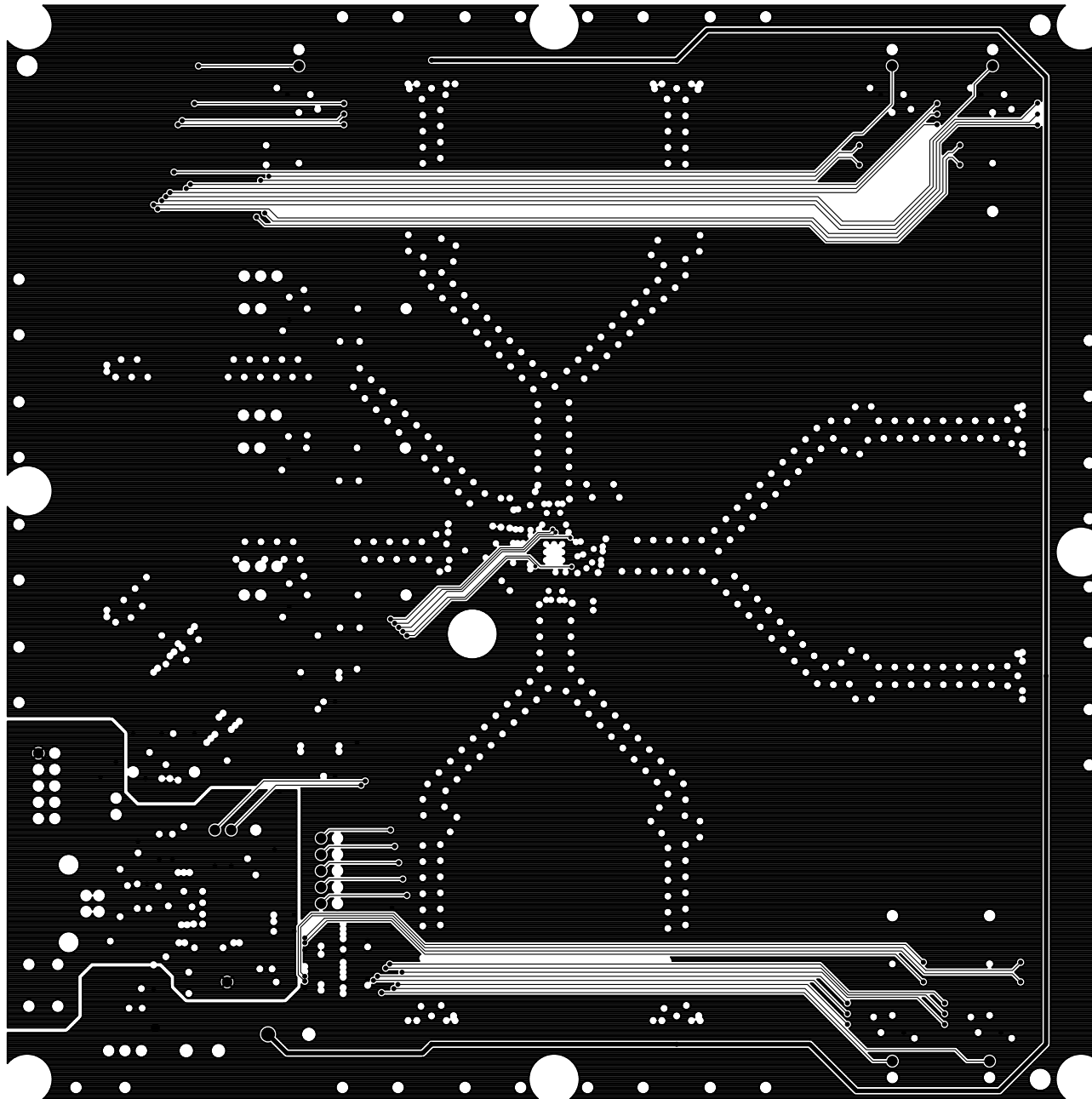
PRIMARY SIDE



LAYER 02

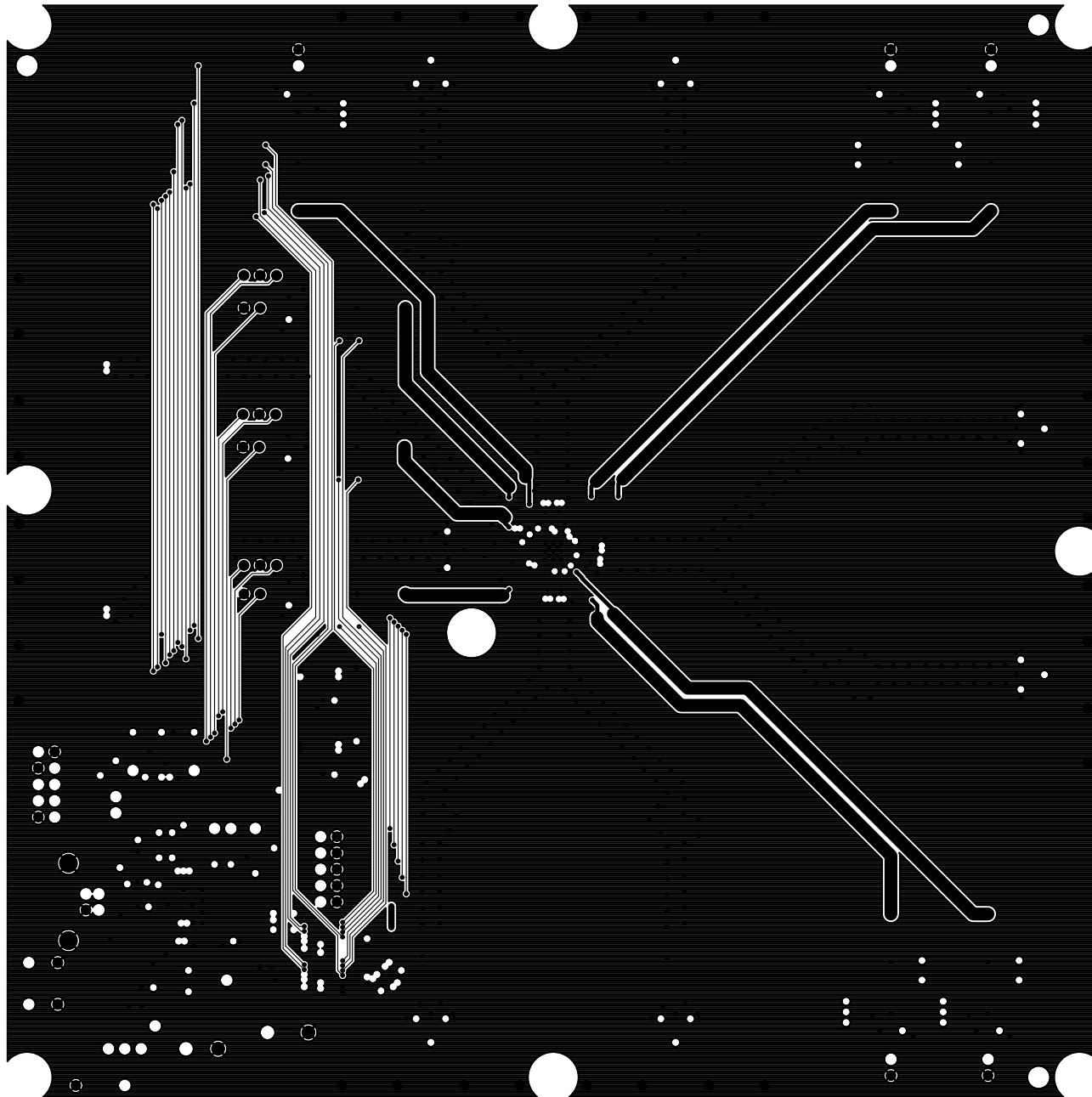


LAYER 03

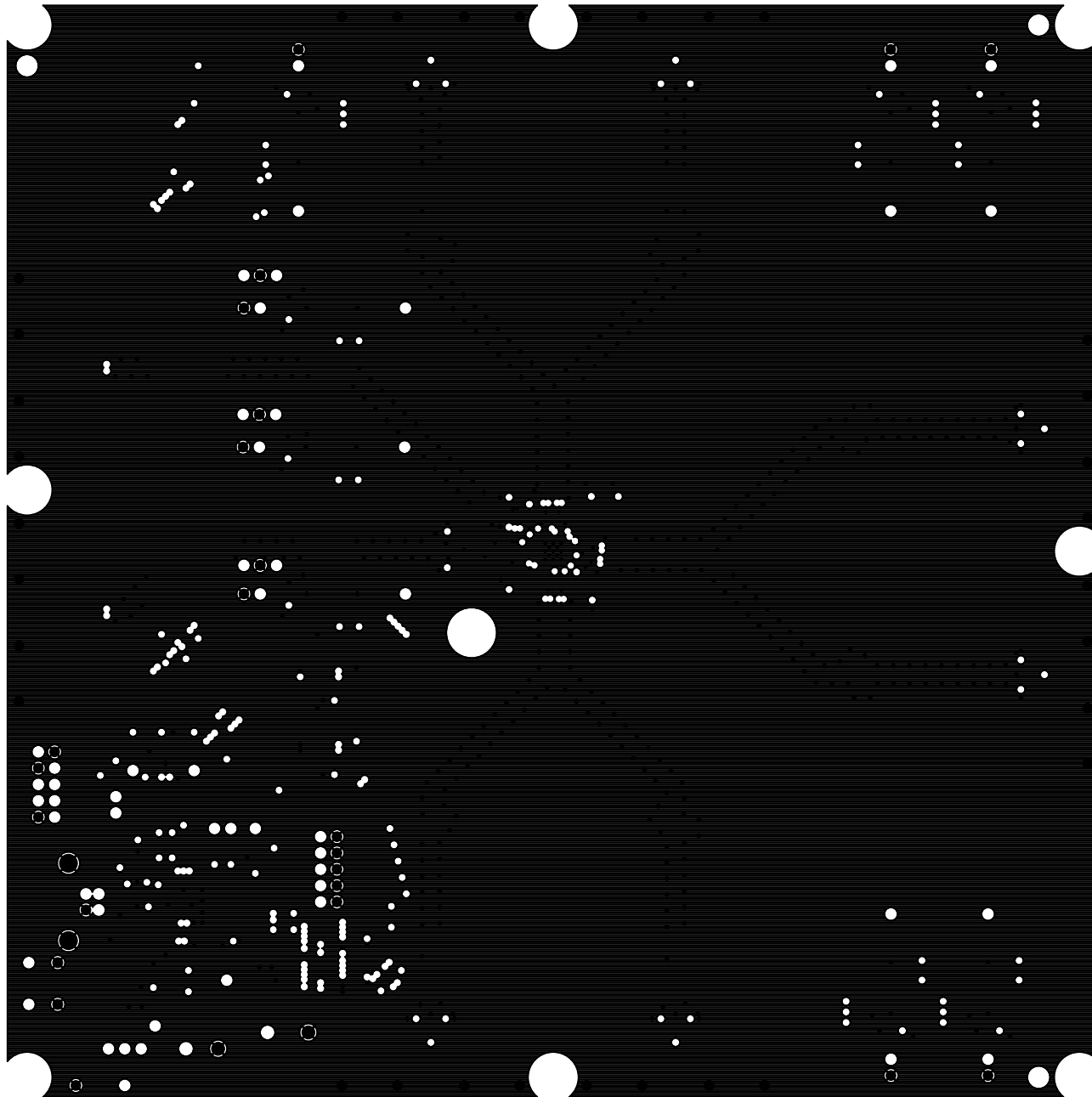


LAYER 04

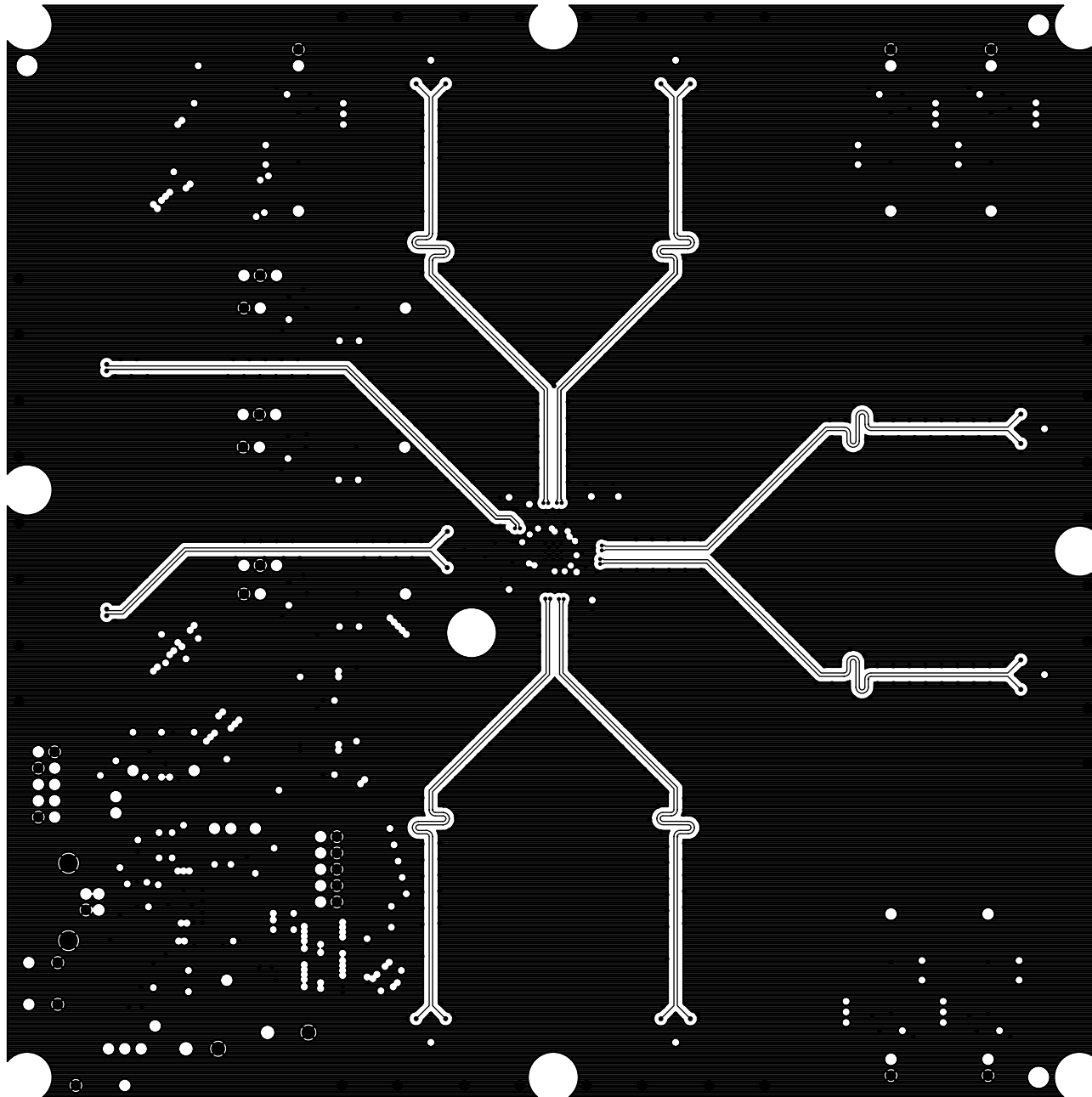




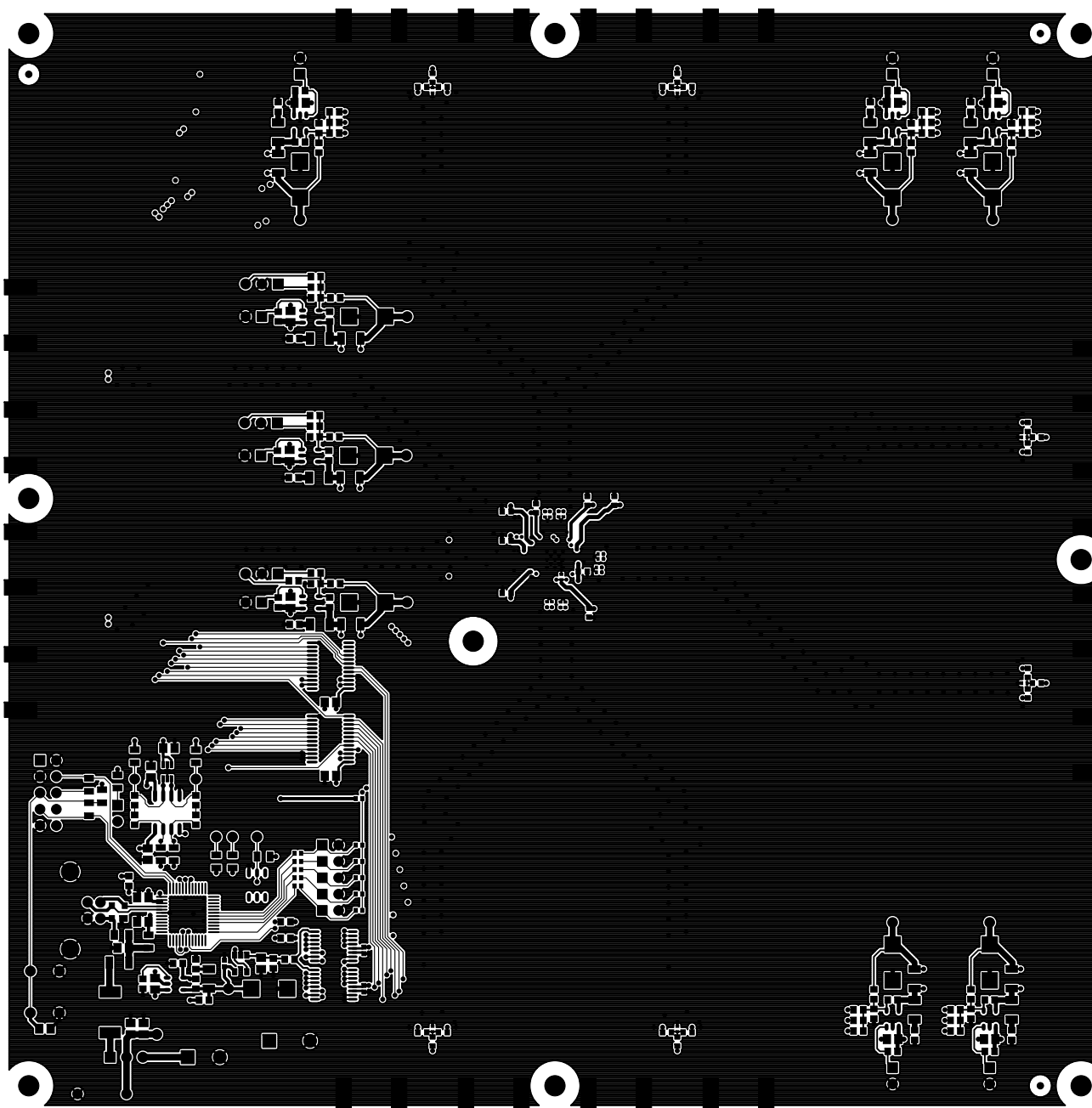
LAYER 05



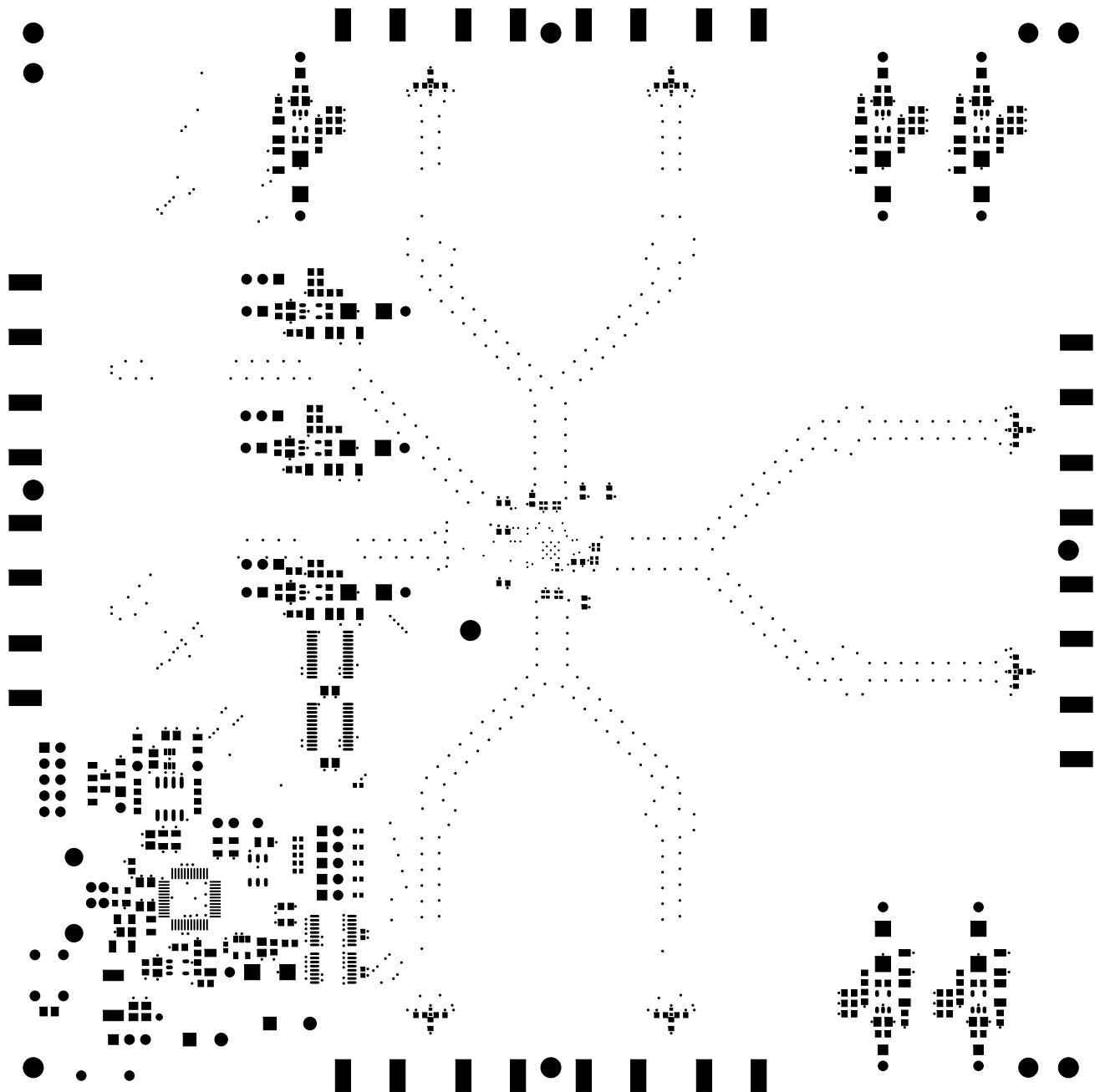
LAYER 06



LAYER 07



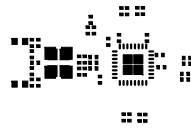
SECONDARY SIDE



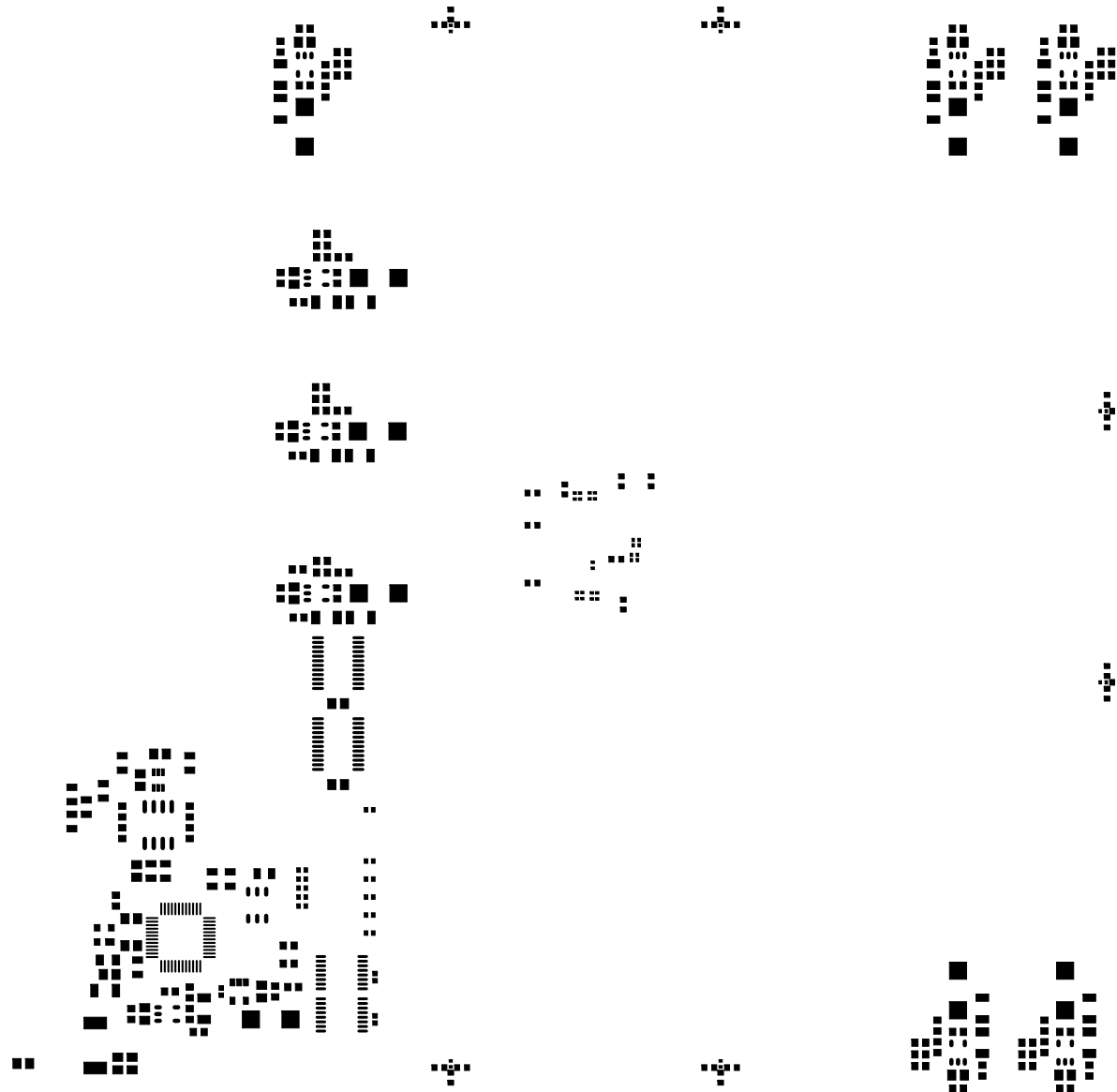
SECONDARY SOLDER MASK







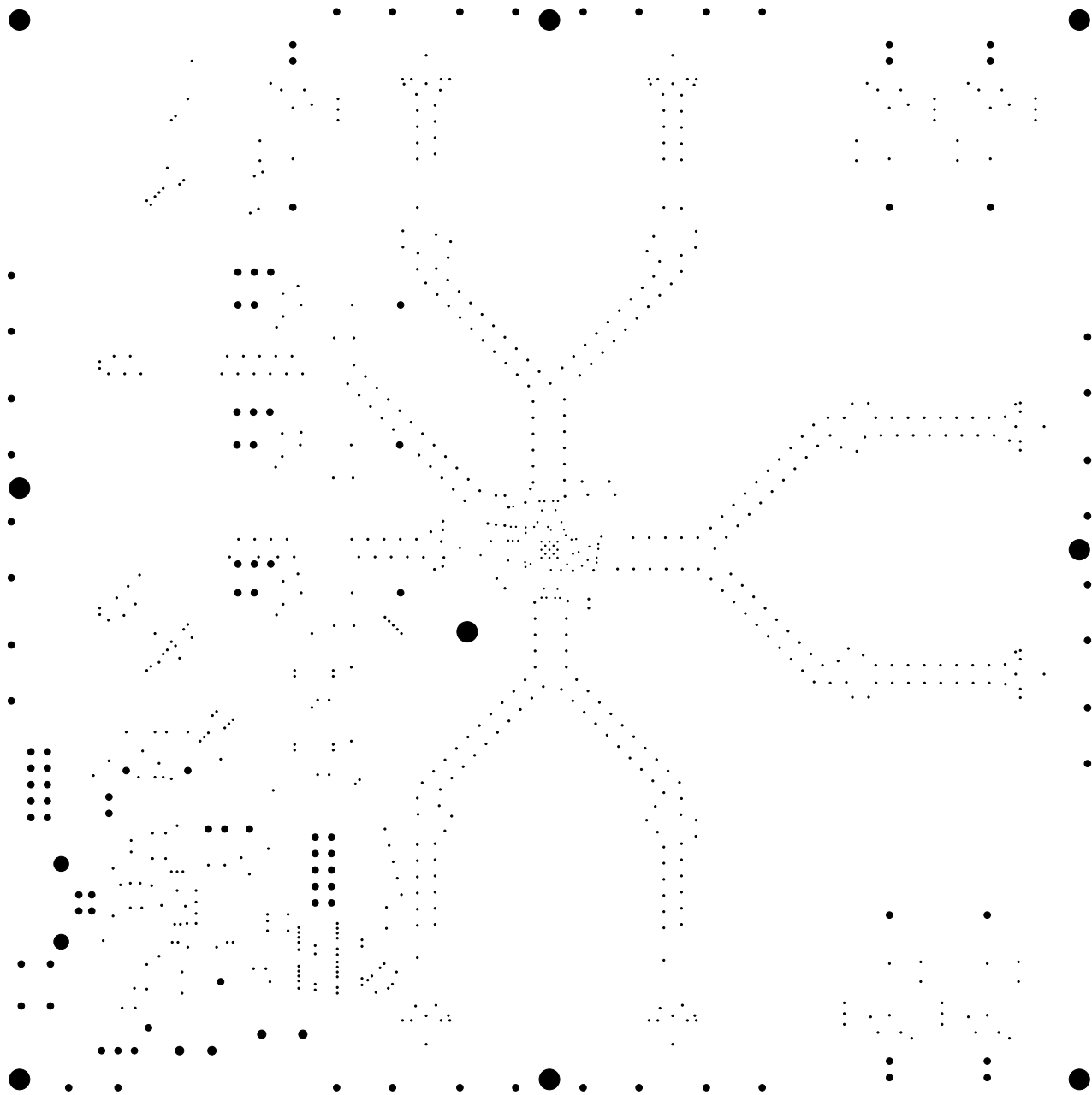
PRIMARY SOLDER PASTE

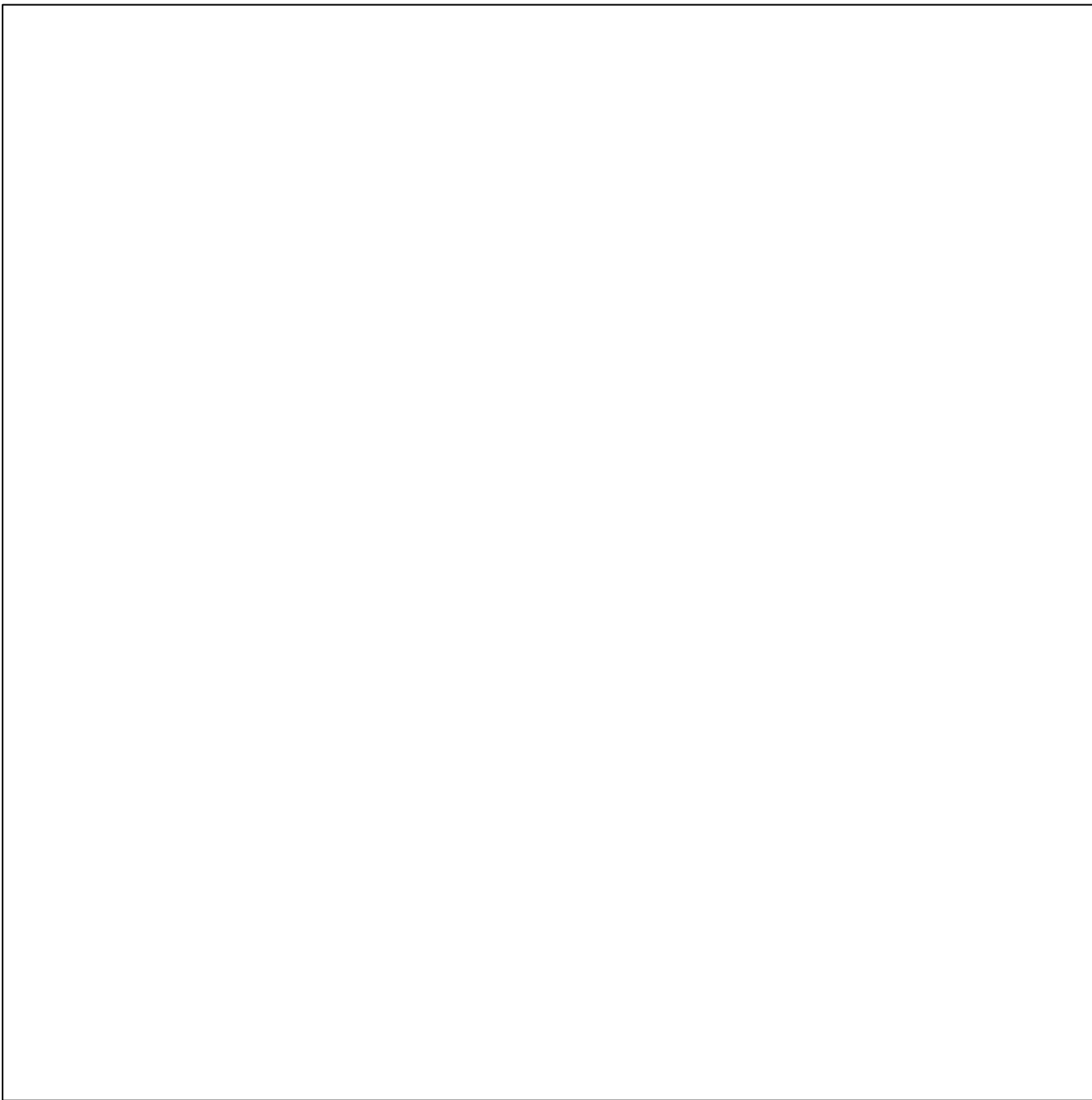


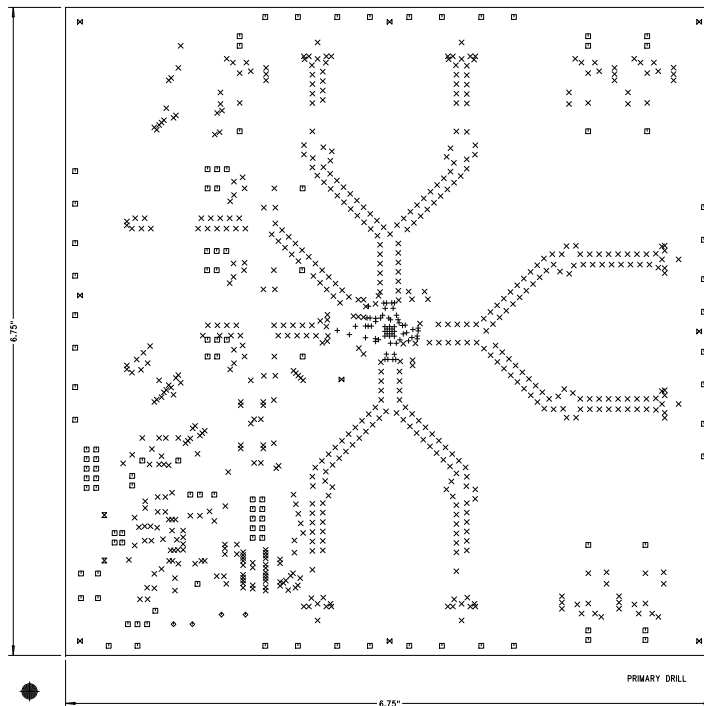
SECONDARY SOLDER PASTE











NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26,83,98 WITH A DECOMPOSITION TEMPERATURE  $\geq 345^{\circ}\text{C}$ , COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 0.5 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE  $\pm 0.003$ ".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE  $0.062^{\circ} \pm 10\%$ .
10. WARP/TWIST SHALL NOT EXCEED 1.0X.
11. FINISH SHALL BE LPL, BLUE SMOGC, ENG BOTH SIDES.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. INTERNAL 0.175MM TRACES TO BE 50 OHM  $Z_0 \pm 5\%$ .
- EXTERNAL 0.275MM TRACES TO BE 50 OHM  $Z_0 \pm 5\%$ .
14. VENDOR TO PROVIDE PCB MICRO-SECTION OF COUPON AREA & TDR TEST REPORT.
15. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT

LAYER STACKUP		FILE NAMES
PRIMARY SILKSCREEN		53320FN32-CEVB_PSS.PHO
PRIMARY SOLDERMASK		53320FN32-CEVB_PSM.PHO
PRIMARY SIDE		53320FN32-CEVB_PRL.PHO
375HR		5.7MIL THK
GROUND PLANE		53320FN32-CEVB_L02.PHO
375HR		8MIL THK
GROUND PLANE		53320FN32-CEVB_L03.PHO
FR-4 IPC-4101/26,83,98		9.64MIL THK
DIG ROUTE/GND		53320FN32-CEVB_L04.PHO
FR-4 IPC-4101/26,83,98		8MIL THK
DIG ROUTE, VDD0x, GND		53320FN32-CEVB_L05.PHO
FR-4 IPC-4101/26,83,98		9.64MIL THK
GROUND PLANE		53320FN32-CEVB_L06.PHO
375HR		8MIL THK
RF ROUTE/GND		53320FN32-CEVB_L07.PHO
375HR		5.7MIL THK
SECONDARY SIDE		53320FN32-CEVB_SEC.PHO
SECONDARY SOLDERMASK		53320FN32-CEVB_SSM.PHO
SECONDARY SILKSCREEN		53320FN32-CEVB_SSS.PHO

SCALE: NONE

SIZE	QTY	SYM	PLT	TOOL	TOL
0.008	61	+	P	1	$+0/-0.008$
0.012	670	X	P	2	$+0/-0.012$
0.040	107	□	P	3	$\pm 0.003$
0.052	4	◇	P	4	$\pm 0.003$
0.091	2	⊗	P	5	$\pm 0.003$
0.125	9	⊗	N	6	$\pm 0.003$

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DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH DIMENSIONS IN BRACKETS ( ) ARE IN MILLIMETERS INTERPRET DRAWING PER MIL-D-8836		TOLERANCES		NAME: <b>Si5332-6EX-EVB</b>	
HOLE TOLERANCES PER TAB07		DESIGN: HS		SIZE: <b>C</b>	
DECIMALS ANGLES SURFACES		LAYOUT: AA		PART NUMBER:	
xxx +/-		PART TO BE FREE OF BURRS		SCALE: <b>1:1</b>	
NEW ENDS NEW FORM NEW RELY		DO NOT SCALE DRAWING		FABRICATION DRAWING	
MIL MIL MIL				SHEET 1 OF 1	